IN THE UNITED STATES PATENT AND TRADEMARK OFFIC

Applicant: Timothy J. Brosnihan et al

Art Unit : 2814

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Title

: METHOD OF FABRICATING A MICROFABRICATED HIGH ASPECT RATIO

DEVICE WITH ELECTRICAL ISOLATION

Commissioner for Patents Washington, D.C. 20231

RESPONSE

In response to the action mailed June 6, 2001, please amend the application as follows:

In the title:

Please amend the title to read: METHOD OF FABRICATING A

MICROFABRICATED HIGH ASPECT RATIO DEVICE WITH ELECTRICAL ISOLATION.

In the claims:

Please amend the claims as follows:

1. (Amended) A method of fabricaling a microelectromechanical system, comprising:

providing a substrate having a device layer;

etching a first trench in the device layer, the first trench surrounding a first region of the substrate;

depositing a dielectric isolation layer in the first trench to electrically isolate the first region from a second region of the substrate; and

etching a second trench in the device layer, the second trench located in first region and defining a microstructure.

CERTIFICATE OF MAILING BY FIRST CLASS MAIL

I hereby certify under 37 CFR §1.8(a) that this correspondence is being deposited with the United States Postal Service as first class mail with sufficient postage on the date indicated below and is addressed to the Commissioner for Patents, Washington, D.C. 20231.

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